



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D
<i>* : Required Field</i>			

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2013-04-17
Contact Name *	Refer to "Supplier Comment" section	Contact Title	Refer to "Supplier Comment" section
Contact Phone *	Refer to "Supplier Comment" section	Contact Email *	Refer to "Supplier Comment" section
Authorized Representative *	Giuseppe Vitali Palma	Representative Title	AMS & IPD Materials Declaration Champion
Representative Phone *	Refer to "Supplier Comment" section	Representative Email *	Refer to "Supplier Comment" section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/internet/com/support/online_tech_support.jsp		

Uncertainty Statement

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Legal Statement

Supplier Acceptance *	true	Legal Declaration *	Standard
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Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
BAS70KFILM	HJM7*NHBAF70	A	Z55A	2013-04-17
Amount		UoM	Unit type	ST ECOPACK Grade
1.425		mg	Each	ECOPACK® 2

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		
1	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Not Applicable ; if coating is used o	Tin (Sn), matte	Copper Alloy		



Package Designator	Size	Nbr of instances	Shape	
CHP	1.2X0.8X0.6	1	flat	
Comment	Package: SOD 523			

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
Product(s) meets EU RoHS requirement without any exemptions	true
Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
Product(s) meets EU RoHS requirements by application of the selected exemption(s)	false
Product(s) does not meet EU RoHS requirements and is not under exemptions	false
Product(s) is obsolete, no information is available	false
Product(s) is unknown, no information is available	false
Exemption Id.	Description

QueryList :REACH-19 December 2012				
Query				Response
The product does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	HJM7*NHBAF70					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Silicon Die	Other inorganic materials	0.029	mg		Silicon Die	Si	7440-21-3		0.029	mg	1000000	20
leadframe	Copper & its alloys	0.582	mg		Alloy	Mn	7439-96-5		0.004	mg	6873	3
leadframe		0.582	mg		Alloy	Fe	7439-89-6		0.335	mg	575601	235
leadframe		0.582	mg		Alloy	Cr	7440-47-3		0.001	mg	1718	1
leadframe		0.582	mg		Alloy	Co	7440-48-4		0.003	mg	5155	2
leadframe		0.582	mg		Alloy	Si	7440-21-3		0.001	mg	1718	1
leadframe		0.582	mg		Nickel (external applications only)	Nickel	7440-02-0		0.238	mg	408935	167
leadframe coating		0.022	mg		coating	Ag	7440-22-4		0.022	mg	1000000	15
bonding wire	Precious metals	0.01	mg		bonding wire	Au	7440-57-5		0.01	mg	1000000	7
Encapsulation		0.754	mg		Molding compound	SiO2	60676-86-0		0.657	mg	871353	461
Encapsulation		0.754	mg		Molding compound	Epoxy Resin	29690-82-2		0.038	mg	50398	27
Encapsulation		0.754	mg		Molding compound	Phenol Resin	26834-02-6		0.038	mg	50398	27
Encapsulation		0.754	mg		Molding compound	Aromatic poly-phosphate	Proprietary		0.019	mg	25199	13
Encapsulation		0.754	mg		Molding compound	Carbon black	1333-86-4		0.002	mg	2653	1
Finishing	Other inorganic materials	0.028	mg		Connection coating	Sn	7440-31-5		0.028	mg	1000000	20